

Towards a roll-to-roll ALD process

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Outline

- Basics of atomic layer deposition (ALD)
- General configuration of batch process
- Configurations for a roll-to-roll process
- Continuous ALD process
- Process characteristics
- o Next steps
- Conclusions



Basics of ALD process

- Chemical vapour deposition process. Ο
- Typically uses two precursors to form film material. Ο
 - for example aluminium oxide (most studied material)
 - uses trimethyl aluminium (TMÀ) and water as the precursors
- Precursors must have high enough vapour pressure Ο
 - can be liquid, solid or gas
 liquid: TMA, TiCl₄, water

 - solid: $HfCl_4$, Cu hexafluoroacetylacetonate
 - gas: ozone, hydrogen sulphide
- These precursors normally react spontaneously when they come in contact Ο
 - form a powder in the gas phase, no use for film deposition
 - want a surface reaction so that oxide is only formed on the substrate
- Solution: Only allow precursor to reach the substrate one at a time Ο
 - no reaction in the gas phase —
 - reaction only occurs between molecules which have been bonded to the surface



Process cycle repeated as many times as required







Characteristics of ALD

- Film growth can be completely conformal, even on complex shapes, in pores and holes.
- Film uniformity is excellent.
- Surface area for coating can be large.
 - many square metres
- Film thickness is proportional to the number of deposition cycles.
- Deposition speed is suitable for production processes



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- Film thickness is proportional to the number of deposition cycles.
- Deposition speed is suitable for production processes
- Needs a batch process
- For very large scale production, a roll-to-roll system is needed
 - web treatments
 - packaging, plastic electronics, etc.



Needs a change of philosophy

 Batch system uses a *stationary* substrate and *time sequenced precursor and gas pulses* to obtain the sequential exposure of the substrate to different materials.

However

Same effect can be achieved using *constant* gas flow zones *separated in space* and a *moving* substrate in order to obtain the time sequential exposure.

Several advantages

- Moving substrate allows a continuous coating process which lends itself to roll-to-roll coating.
- Constant gas flows means no time switching of gases.
- Cycle time depends on speed of movement of substrate between the gas flow zones.



How to achieve this?

- A number of schemes have been proposed for achieving continuous coating based on this principle.
- Critical factor is to ensure no intermixing of precursor gases.



Possible roll-to-roll systems

US2007281089A1 General Electric 2007





US2007224348A1 Planar 2007



Possible issues:

- Cracking and abrasion of web as it passes over rollers
- o Both sides are coated
- Good gas separation may be difficult
- Easy to incorporate multiple cycles of deposition
- Has been demonstrated by Lotus (Planar spin-off) in USA
- Web speeds of several 100s m/min



US2007238311A1 Kodak 2007



Separation between substrate and coating head is set by levitation of the head due to the gas pressure

MIICS 2010









- Coating head is scanned over rigid substrate
- Each pass gives multiple cycles depending on construction of coating head
- Can be used at atmospheric pressure





• Could be perhaps extended to a web coating system.





Stable ZnO thin film transistors by fast open air atomic layer deposition

Applied Physics Letters 92, 192101 2008



ASTRaL approach

- TEKES project: Continuous Atomic Layer Deposition Process (CALD)
- Aim: to develop the technology for roll-to-roll coating for diffusion barrier layers.
- Build an experimental system which would show the feasibility of roll-to-roll coating
- Based on the movement of a flexible substrate through precursor and purge gas zones.



System configuration













courtesy Beneq Oy



System parameters

- Substrate maximum size: 310 mm x 120 mm
- Rotational speed: up to 1000 rpm
- Chamber temperature: room temperature to 200 C
- Current process: aluminium oxide from TMA + water
- Planned future work: titanium oxide
- Carrying out basic deposition studies
 - ALD deposition parameters
 - uniformity
 - speed
 - precursor efficiency



Preliminary results

- \circ ALD growth achieved for Al₂O₃ from TMA and H₂O
- Deposition temperature 100 C
- Substrates PET sheet metallised with Ti (for ease of measurement)
- Deposition rate shows a region independent of precursor dose
 - deposition rate ~1.2 Å/revolution
 - conventional ALD at the same temperature with the same precursors gives ~1 Å/cycle
- Deposition rate is independent of rotation speed within certain ranges depending on precursor flow rate and other gas flow parameters.
- Uniformity is good over the whole substrate
- High precursor efficiency: estimated to be >80%



Next steps

- Continue to explore gas flow parameter space
- Measure diffusion barrier performance
- Deposit titanium oxide (should be an easier process than aluminium oxide)
- Set out design principles for roll-to-roll system
 - current system gives one layer per revolution
 - needs to be increased for practical roll-to-roll system



WATCH THIS SPACE!